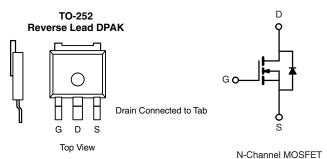


PRODUCT SUMMARY				
V <sub>DS</sub> (V)	100			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 V$	0.025			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 V$	0.029			
I <sub>D</sub> (A)	40			
Configuration	Single			



#### **FEATURES**

- TrenchFET<sup>®</sup> Power MOSFET
- Package with Low Thermal Resistance
- 100 %  $R_q$  and UIS Tested
- AEC-Q101 Qualified
- Material categorization: For definitions of compliance please see www.freescale.net.cn



ORDERING INFORMATION	
Package	TO-252 Reverse Lead DPAK
Lead (Pb)-free and Halogen-free	SQR40N10-25-GE3

ABSOLUTE MAXIMUM RATINGS	(T <sub>C</sub> = 25 °C, unles	s otherwise noted	(k		
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V <sub>DS</sub>	100	V	
Gate-Source Voltage		V <sub>GS</sub>	± 20	V	
Continuous Drain Current	$T_C = 25 \ ^{\circ}C^a$	1	40		
Continuous Drain Current	T <sub>C</sub> = 125 °C	· I <sub>D</sub>	26		
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	40	А	
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	160		
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	40		
Single Pulse Avalanche Energy		E <sub>AS</sub>	80	mJ	
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	D	136	W	
	T <sub>C</sub> = 125 °C	P <sub>D</sub>	45		
Operating Junction and Storage Temperature F	Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 175	°C	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB Mount <sup>c</sup>	R <sub>thJA</sub>	50	°C/W
Junction-to-Case (Drain)		R <sub>thJC</sub>	1.1	0/10

#### Notes

a. Package limited.

b. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%.$ 

c. When mounted on 1" square PCB (FR-4 material).



PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static	·						
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 V, I_D = 250 \mu A$		100	-	-	V
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	1.5	-	2.5	V
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	0 V, $V_{GS} = \pm 20 V$	-	-	± 100	nA
		$V_{GS} = 0 V$	V <sub>DS</sub> = 100 V	-	-	1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = 0 V$	$V_{DS} = 100 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$	-	-	50	μA
		$V_{GS} = 0 V$	V <sub>DS</sub> = 100 V, T <sub>J</sub> = 175 °C	-	-	250	1
On-State Drain Currenta	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \ge 5 V$	50	-	-	Α
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 40 A	-	0.019	0.025	Ω
Drain Source On State Desistence?	P	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 40 A, T <sub>J</sub> = 125 °C	-	-	0.050	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 40 A, T <sub>J</sub> = 175 °C	-	-	0.063	
		$V_{GS} = 4.5 V$	I <sub>D</sub> = 20 A	-	0.021	0.029	
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 40 A		-	73	-	S
Dynamic <sup>b</sup>	·						•
Input Capacitance	C <sub>iss</sub>			-	2703	3380	
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V V <sub>DS</sub> = 25 V, f = 1 MHz		-	312	390	pF
Reverse Transfer Capacitance	C <sub>rss</sub>			-	127	160	
Total Gate Charge <sup>c</sup>	Qg			-	46	70	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$V_{DS} = 50 \text{ V}, I_D = 40 \text{ A}$	-	8.2	-	nC
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			-	13	-	
Gate Resistance	Rg	f = 1 MHz		1	2	3.1	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			-	11	17	
Rise Time <sup>c</sup>	tr	$\label{eq:VDD} \begin{array}{l} V_{\text{DD}} = 50 \; V, \; R_{\text{L}} = 1.25 \; \Omega \\ I_{\text{D}} \cong 40 \; A, \; V_{\text{GEN}} = 10 \; V, \; R_{\text{g}} = 1 \; \Omega \end{array}$		-	11	17	- ns
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			-	27	41	
Fall Time <sup>c</sup>	t <sub>f</sub>			-	6	9	
Source-Drain Diode Ratings and Char	acteristics <sup>b</sup>						
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	160	Α
Forward Voltage	V <sub>SD</sub>	$I_{\rm F} = 40$ A, $V_{\rm GS} = 0$ V		-	0.9	1.5	V

Notes

a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

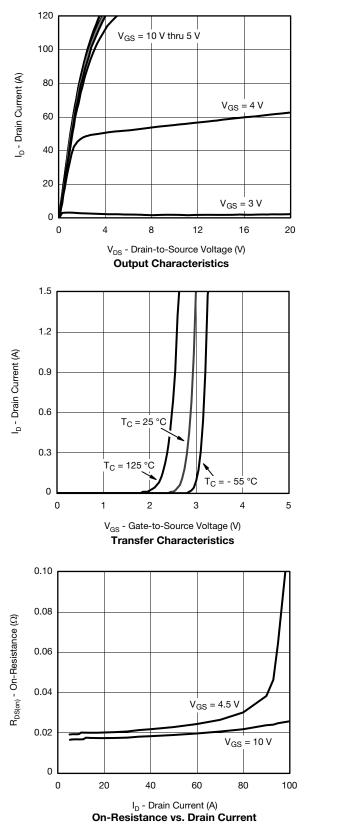
b. Guaranteed by design, not subject to production testing.

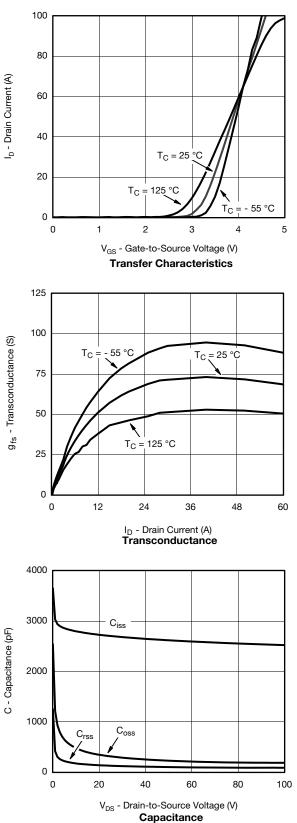
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



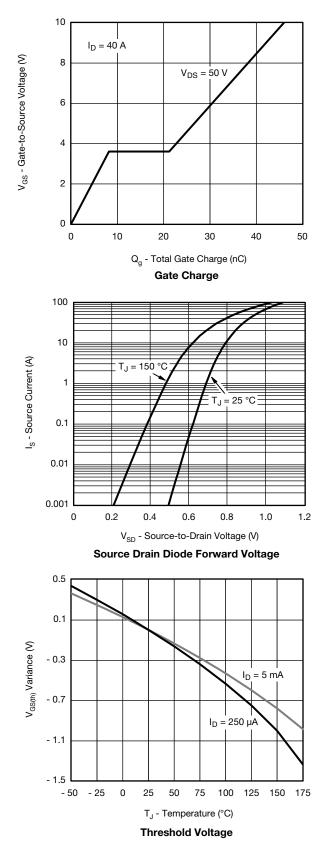
**TYPICAL CHARACTERISTICS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)

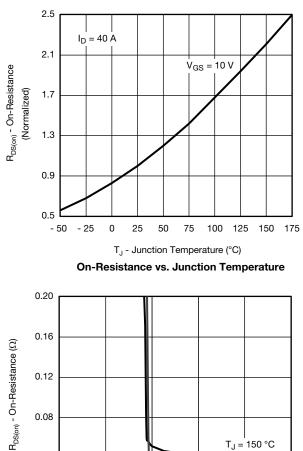


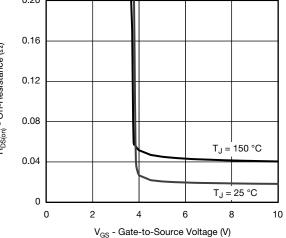




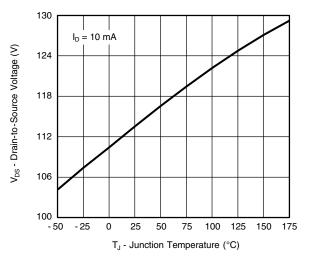
TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)







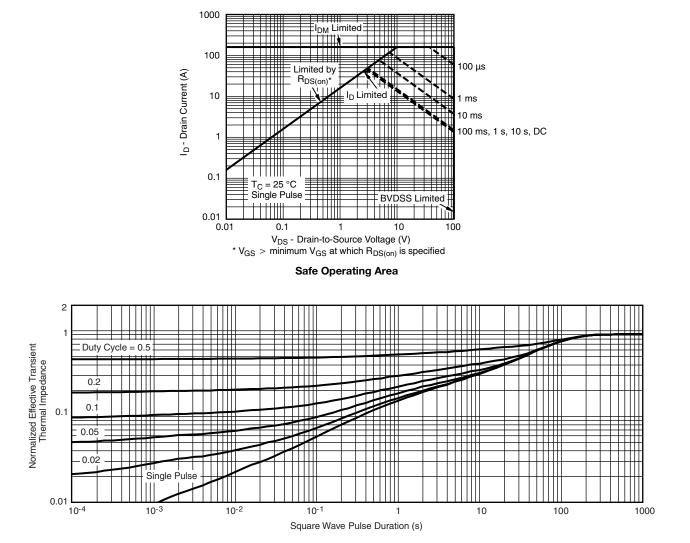
**On-Resistance vs. Gate-to-Source Voltage** 



Drain Source Breakdown vs. Junction Temperature



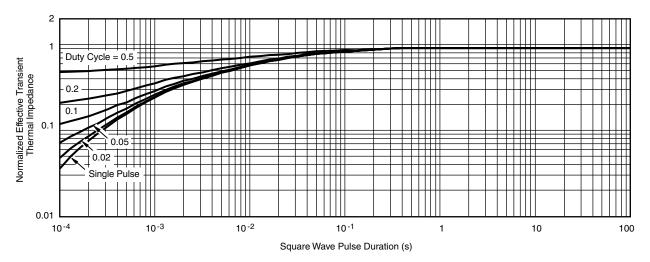
#### THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

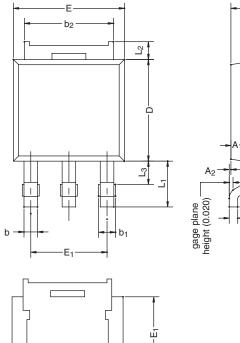
#### Note

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

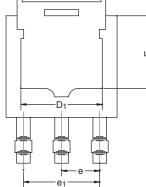


#### **TO-252 REVERSE LEAD CASE OUTLINE**



-C

	MILLIMETERS		INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
А	2.23	2.33	0.088	0.092	
A <sub>1</sub>	0.64	0.89	0.025	0.035	
A <sub>2</sub>	0.03	0.23	0.001	0.009	
b	0.71	0.88	0.028	0.035	
b <sub>1</sub>	0.76	1.14	0.030	0.045	
b <sub>2</sub>	5.23	5.44	0.206	0.214	
С	0.46	0.58	0.018	0.023	
C <sub>1</sub>	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
D <sub>1</sub>	4.49	5.00	0.177	0.197	
Е	6.48	6.73	0.255	0.265	
E <sub>1</sub>	4.32	-	0.170	-	
е	2.28	2.28 BSC		0.090 BSC	
e <sub>1</sub>	4.57	4.57 BSC		0.180 BSC	
Н	9.65	10.41	0.380	0.410	
L	1.40	1.78	0.055	0.070	
L <sub>1</sub>	2.74 BSC		0.108 BSC		
L <sub>2</sub>	0.89	1.27	0.035	0.050	
L <sub>3</sub>	1.15	1.52	0.040	0.060	
ECN: T-08 DWG: 589	3706-Rev. B, 29 4	9-Sep-08			



#### Note

Dimension  $L_3$  for reference only.



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